

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	IMEC	06/03/2016
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
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City:	HSINCHU	
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Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	15180313
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ATTORNEY DOCKET NUMBER:	24061.3394US02	
NAME OF SUBMITTER:	LINDA INGRAM	
SIGNATURE:	/Linda Ingram/	
DATE SIGNED:	05/18/2017	
Total Attachments: 2		
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PATENT ASSIGNMENT

This Agreement, effective as of June 1, 2016 (the "Effective Date"), is by and between IMI C, a non-profit organization established in Leuven, Belgium and residing at Kapeldreef 75, 3001, Leuven, Belgium ("IMEC," the Assignor) and Taiwan Semiconductor Manufacturing Company, Ltd., a Taiwanese corporation, with its principal place of business at 8, Li-Hsin Road 6, 300-077 HsinChu, Taiwan ("TSMC," the Assignee).

WHEREAS, IMEC and TSMC collectively and jointly have an ownership interest in certain new and useful improvements identified collectively as "INVENTIONS" as follows:

**TITLE: METHOD FOR MAUFACTURING A DUAL WORK FUNCTION
SEMICONDUCTOR DEVICE AND THE SEMICONDUCTOR DEVICE
MADE THEREOF**

including the PATENT APPLICATION listed below:

SER. NO.: 12/684,803

FILED ON: JANUARY, 8TH, 2010

WHEREAS, TSMC is desirous of obtaining the entire right, title, and interest in, to and under the INVENTIONS, including the PATENT APPLICATION in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, IMEC has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto TSMC, its successors, legal representatives, and assigns, its entire right, title, and interest in, to and under said INVENTIONS, and said PATENT APPLICATION, and all continuations, divisionals, continuations-in-part, renewals, reissues, and reexaminations, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and IMEC hereby authorizes and requests the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND IMEC HEREBY covenants that it has not licensed or assigned the INVENTIONS to another entity, and that it has its full right to convey its entire interest herein assigned, and that it has not executed, and will not execute, any agreement in conflict herewith.

AND IMEC HEREBY further covenants and agrees that it will communicate to TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

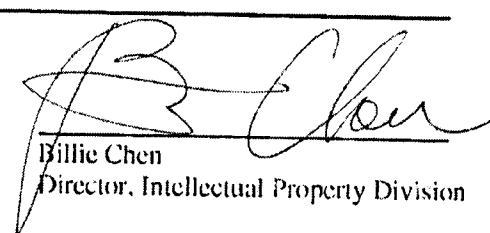
IMEC

Dated: 03/06/16


André Clerix **André Clerix**
Director, IP Portfolio & Litigation Director IP Portfolio & Litigation
European Patent Attorney

TSMC

Dated: June 8, 2016


Billie Chen
Director, Intellectual Property Division